

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|--|---|------------------|
| 1 | 15470 | ((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/24 09:56 |
| 8 | 98 | ((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (potassium adj iodate) and (copper)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/24 10:02 |
| 15 | 65 | (((((Chemical adj mechanical adj polish\$3) or CMP or planariz\$5) and (slurry or composition)) and (potassium adj iodate) and (copper)) and (((remov\$3 near2 rate\$1) or (polish\$3 near2 rate\$1)) same (copper or barrier)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/06/24 10:06 |